

#### **TECHNICAL DATA SHEET**

**Description**: 3.2x1.6x1.1mm Chip Antenna

**PART NUMBER: W3021** 

# Features:

- Frequency 3200-3600MHz
- Size 3.2x1.6x1.1mm
- Keep out area 4.0x6.25mm
- Efficiency 80%
- Gain 2.5dBi
- SMT compatible / MSL3
- RoHS compliant

## **Applications:**

- 3200-3600MHz Radios
- LTE B22, B42
- Miniature SMT chip antenna



All dimensions are in mm

Issue: 1817

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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## **Series: CHIP ANTENNA**

	ELECTRICAL SPECIFICATIONS
Antenna Type	Ceramic Antenna
Frequency	3200-3600 MHz
Nominal Impedance	$50~\Omega$
Return Loss	-6 dB
Radiation Pattern	Omni
Peak Gain	2.5 dBi
Efficiency	80 %
Polarization	Vertical
Power Withstanding	2 W

All measurement data is tested on Pulse 80x37mm evaluation board, position 1.

#### **MECHANICAL SPECIFICATIONS**

Overall Length 3.2x1.6x1.1mm

Weight 33mg

#### **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature  $-40\sim+85^{\circ}$  C Storage Temperature  $-40\sim+85^{\circ}$  C

RoHS Compliant Yes



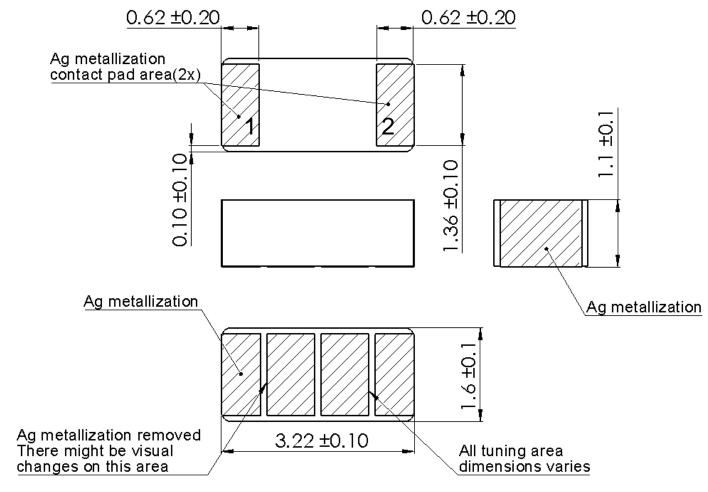


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## **MECHANICAL DRAWING AND TERMINAL CONFIGURATION**



No.	Terminal Name	Terminal Dimensions		
1	Feed / GND	0.62 x 1.36 mm		
2	Feed / GND	0.62 x 1.36 mm		
Antenna is symmetrical. Either of terminals 1 or 2 can be Feed / GND				

Unit:mm



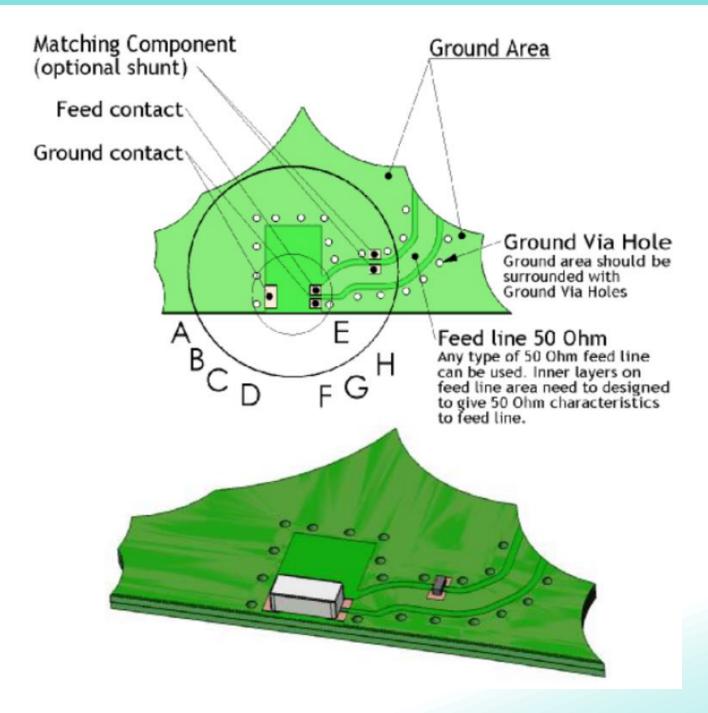


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## **PCB Layout Description**





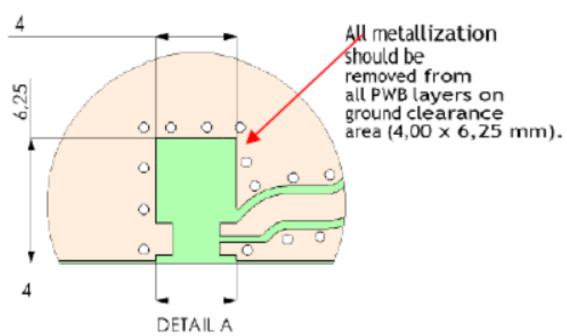
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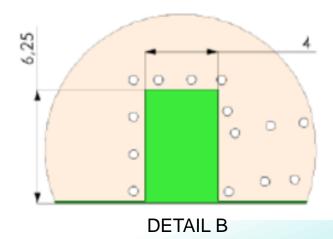
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#### **Ground Clearance Area**

## Ground clearance area (4,00 x 6,25 mm)



## Opening in bottom/inner ground layers



Unit:mm





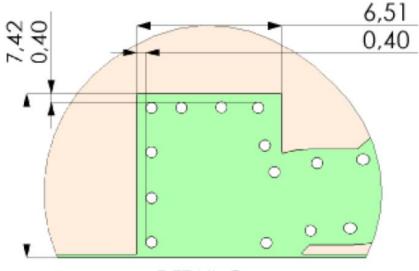
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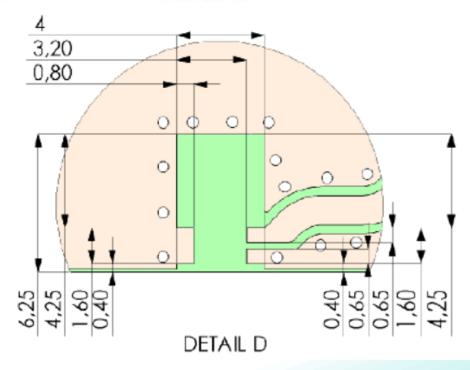
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## Ground Clearance inner (Detail C) and top (Detail D) layers

# Opening in other layers (no ground/ RF)



DETAIL C



Unit:mm





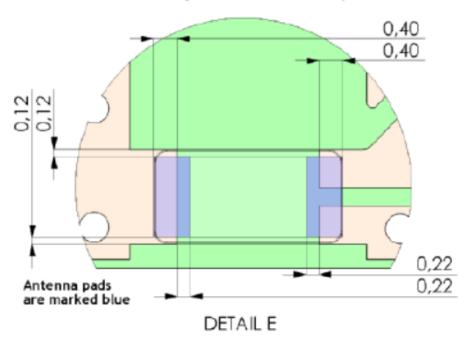
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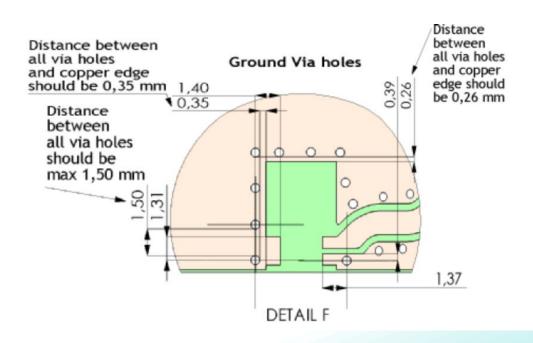
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## Antenna placement (Detail E) and GND via holes (Detail F)

#### Antenna position on PWB layout





Unit:mm



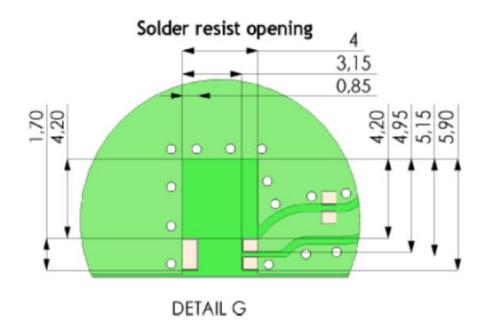


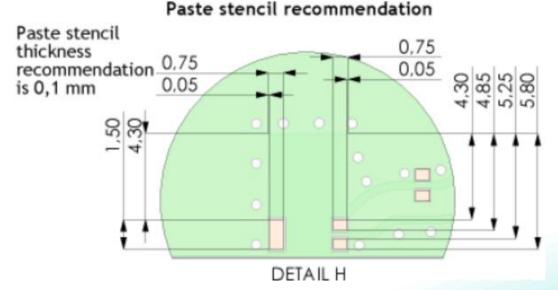
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## Solder resist (Detail G) and Solder paste stencil (Detail H)





Unit:mm



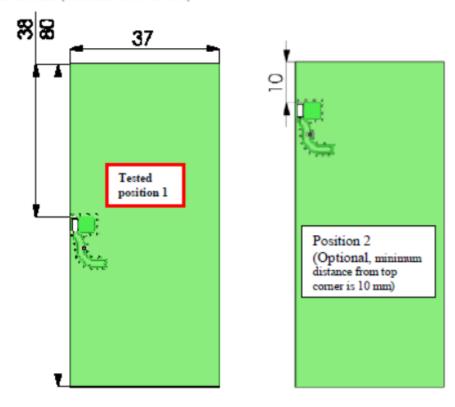
#### **TECHNICAL DATA SHEET**

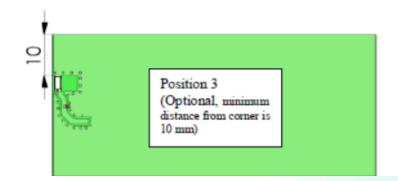
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### Standard evaluation board dimensions

Our test PWB size is 37 x 80 mm, other sized boards can be used depending on customer device size (minimum 35 x 35 mm)





Unit:mm





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## **SMT Sodering Profile**

# Recommendations For Soldering

#### Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s

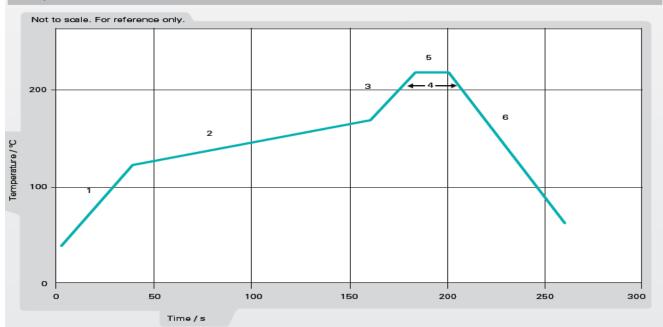


Figure 1. Minimum temperature profile recommendation for reflow soldering process

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## **SMT Sodering Profile**

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

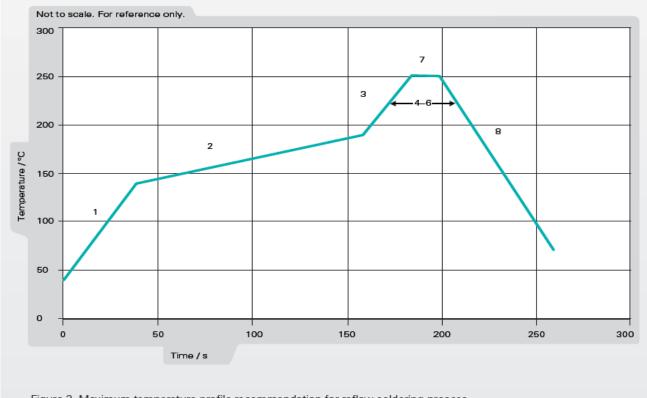


Figure 2. Maximum temperature profile recommendation for reflow soldering process

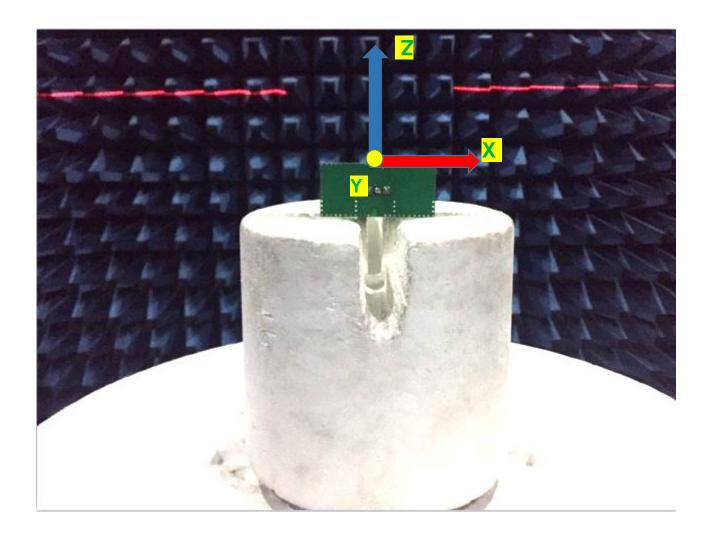


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### **TEST SETUP**



All measurement data is tested on Pulse standard 80x37mm evaluation board, position 1.



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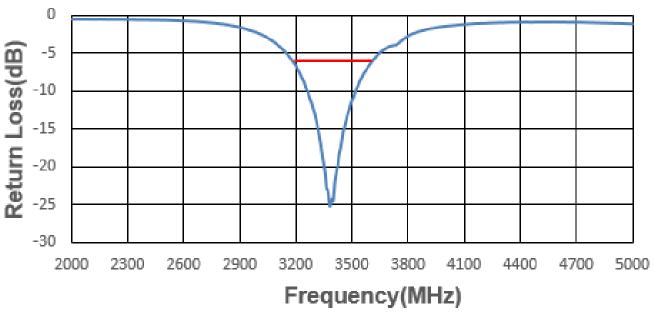
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# Return Loss

Measured on 80\*37mm test board with matching circuit (shunt 0.7pF), and antenna in position1 on PWB layout, see Page9.

## Return Loss

Measured in Pulse China 2018.4.23



——W3021 ——spec 3200-3600





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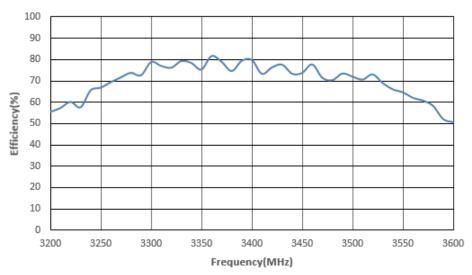
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# Efficiency(%)

Measured on 80\*37mm test board with matching circuit(shunt 0.7pF), and antenna in position1 on PWB layout, see Page9.

Efficiency(%)

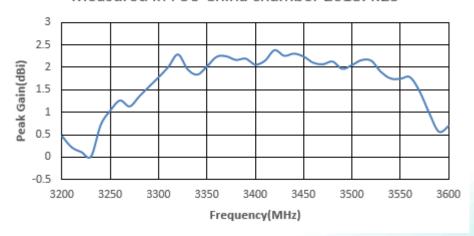
Measured in PSU China chamber 2018.4.23



# Peak Gain (dBi)

### Peak Gain(dBi)

Measured in PSU China chamber 2018.4.23



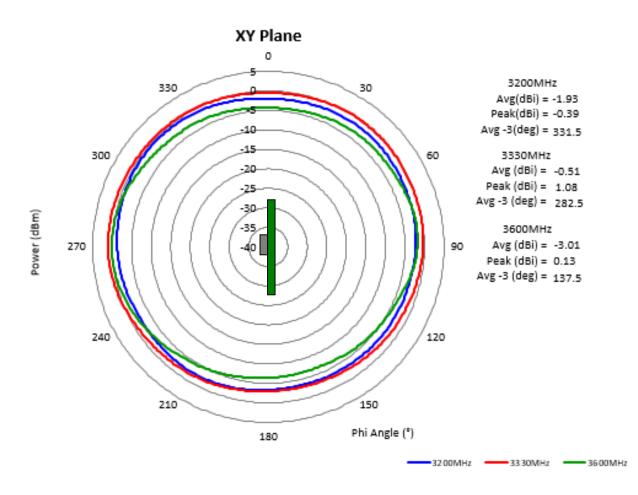




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# Free space radiation pattern







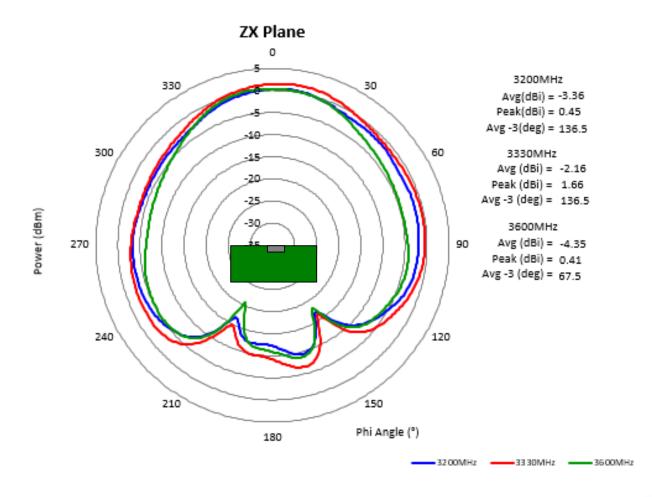




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# Free space radiation pattern





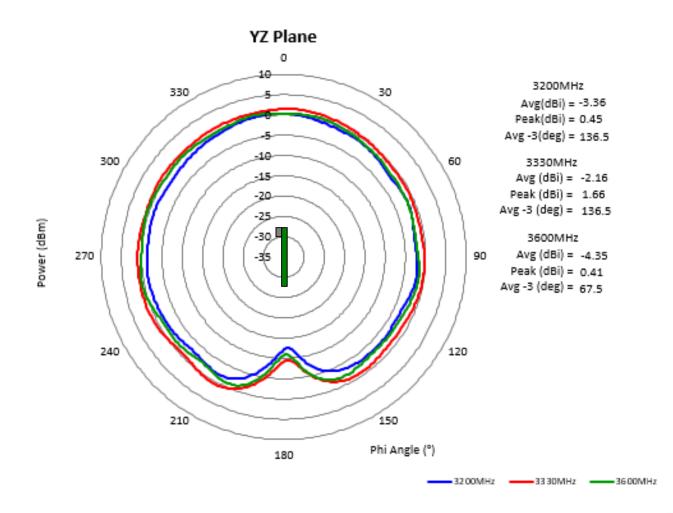




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# Free space radiation pattern





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## **PACKAGING**

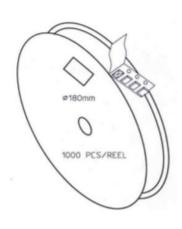
3000pcs antennas per 7" reel

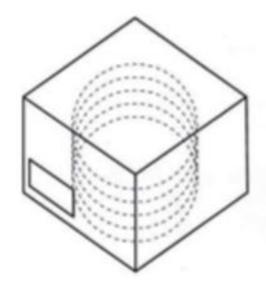
5pcs 7" reel per inner package box

2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm





According to MSL3 packing requirement, MBB-Moisture Barrel Bag, Desiccant, HIC-Humidity Indicator Card, MSID Label, Caution Label are required.